

STM32WB09_QFN32_2L_SMD

MB2161

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Sheet 1: Project overview (this page)

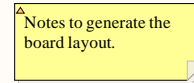
Sheet 2: STM32WB09_QFN32_RefBoard_SMD_2Layers

Legend

General comment such as function title, configuration, ...

Text to be added to silkscreen.

Warning text.



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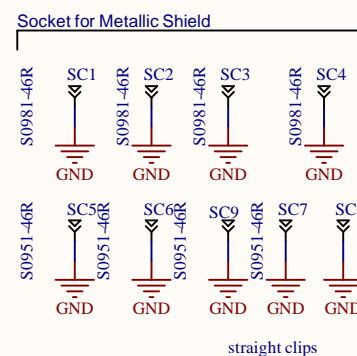
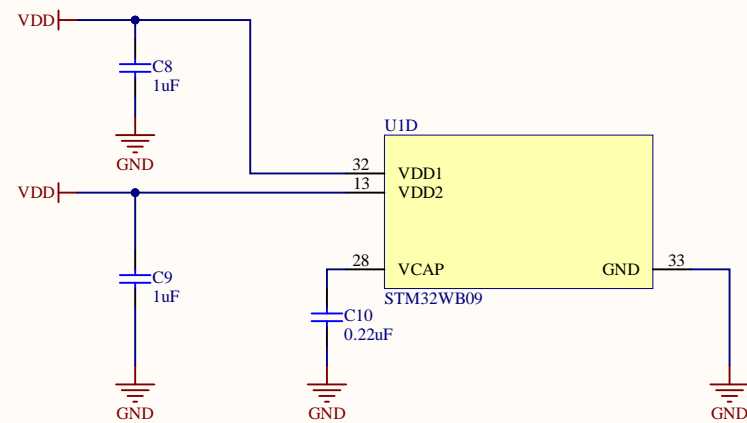
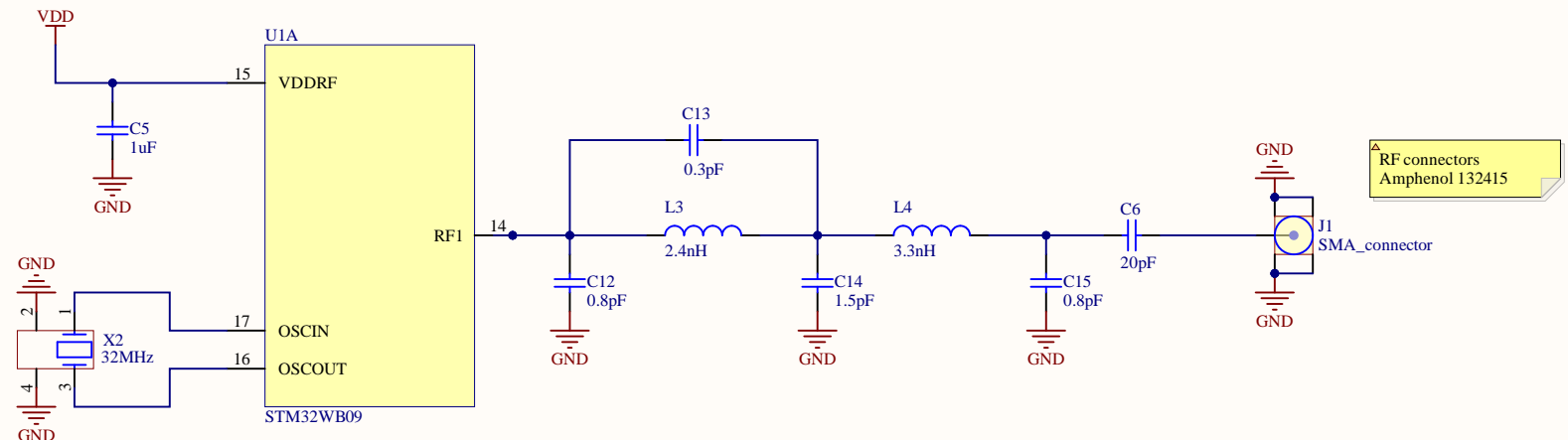
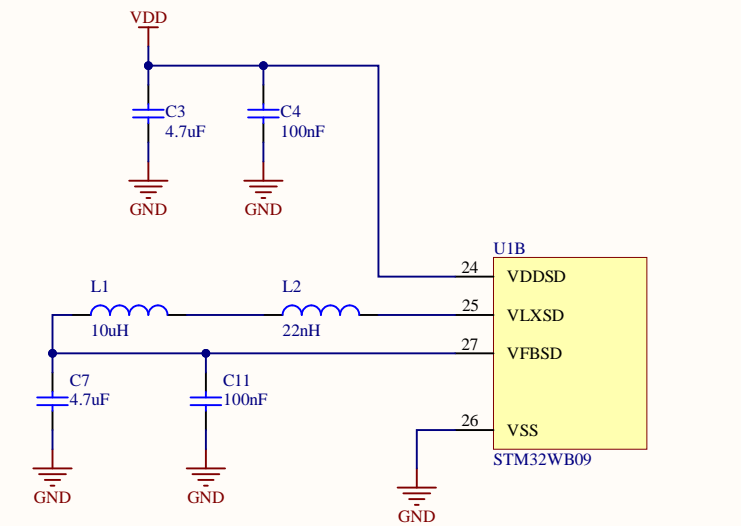
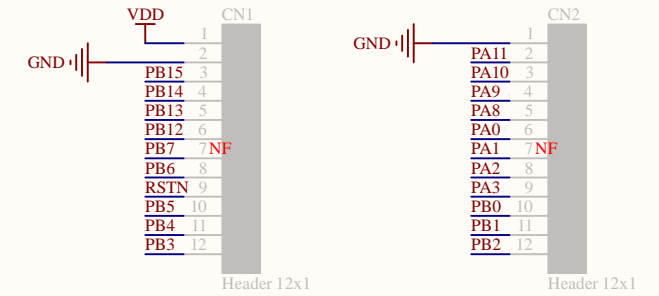
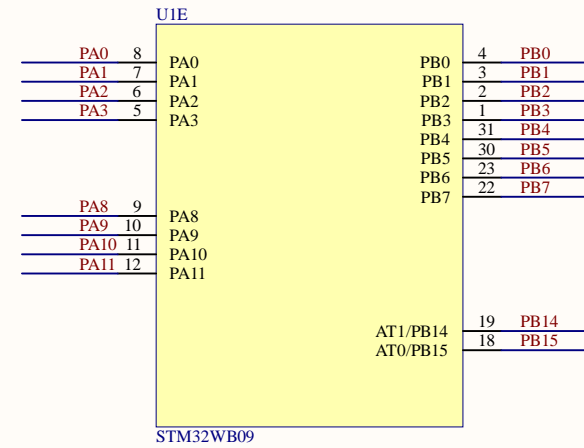
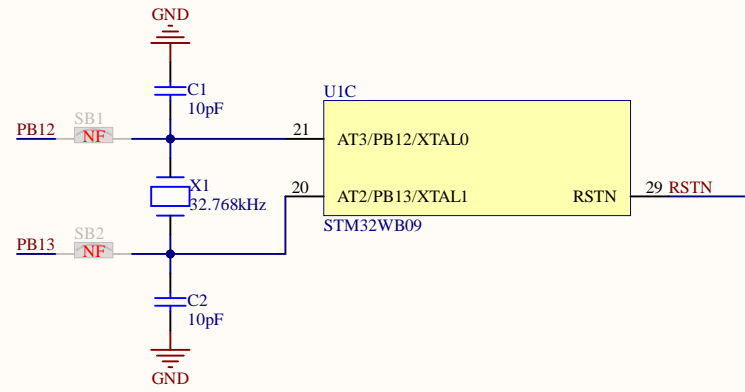
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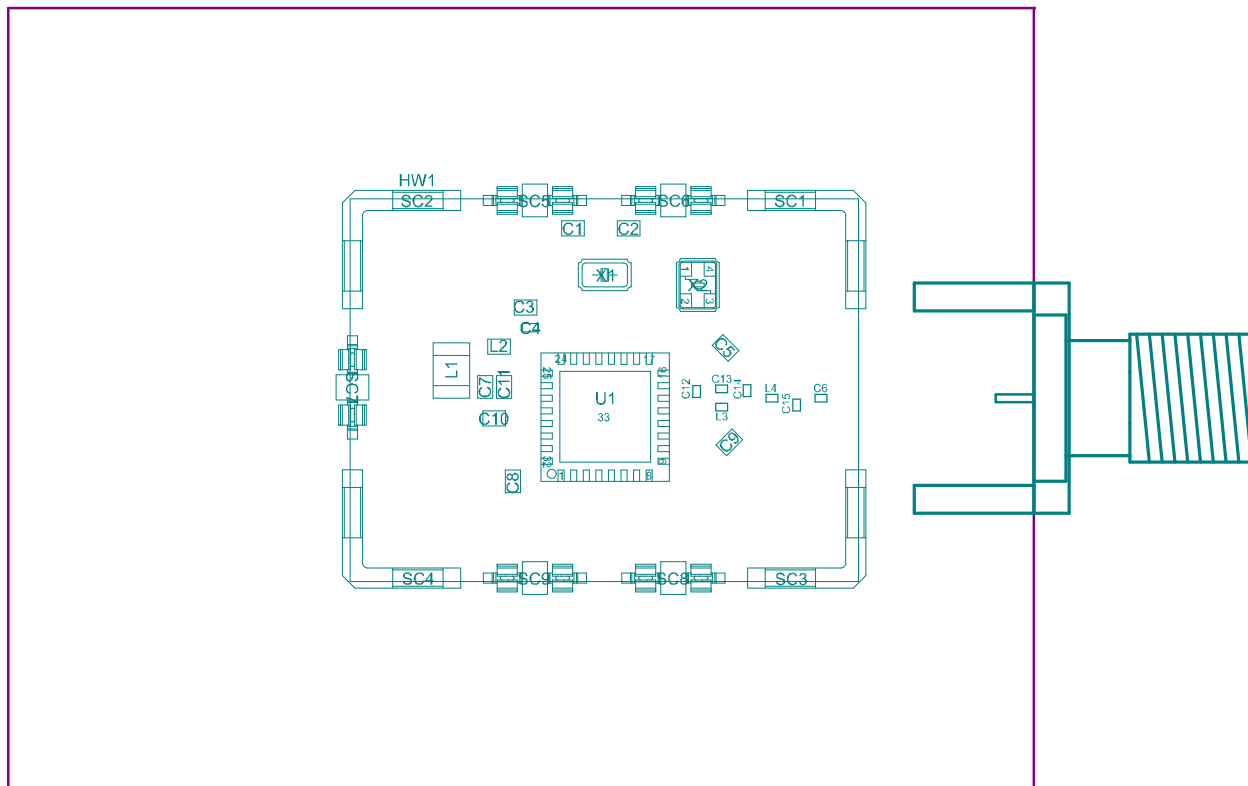
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STM32WB09_QFN32_RefBoard_SMD_2Layers.SchDoc




Title: Project overview		
Project: STM32WB09_QFN32_2L_SMD		
Variant: Variant A		
Revision: A-01		Reference: MB2161
Size: A4	Date: 7 July 2024	Sheet: 1 of 2

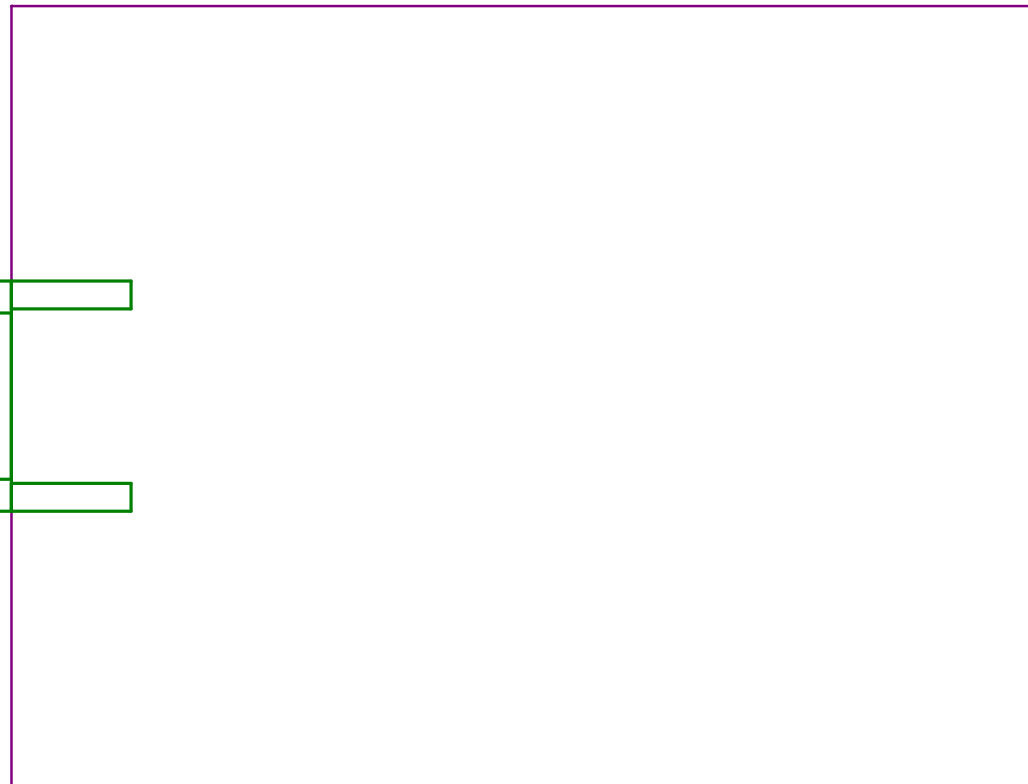
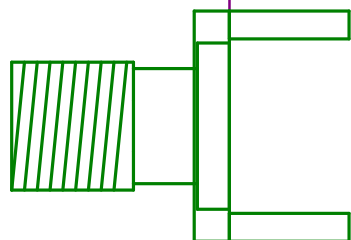






Project: STM32WB09_QFN32_2L_SMD		
Layer: Mechanical 14	Gerber: .GM14	
Variant: Variant A	Ref: MB2161	
Date: 7 July 2024	Rev: A	





Project: STM32WB09_QFN32_2L_SMD	
Layer: Mechanical 15	Gerber: .GM15
Variant: Variant A	Ref: MB2161
Date: 7 July 2024	Rev: A



